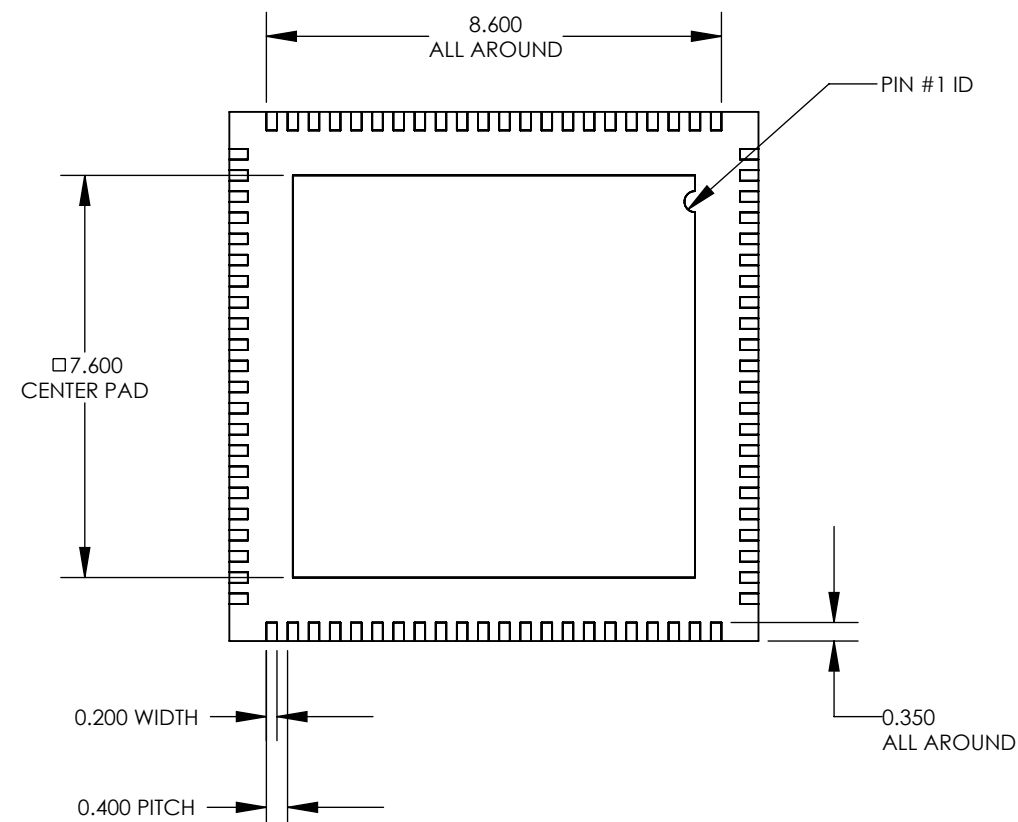
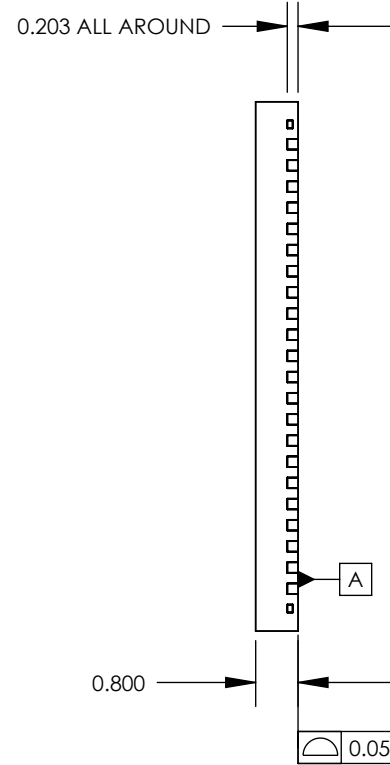
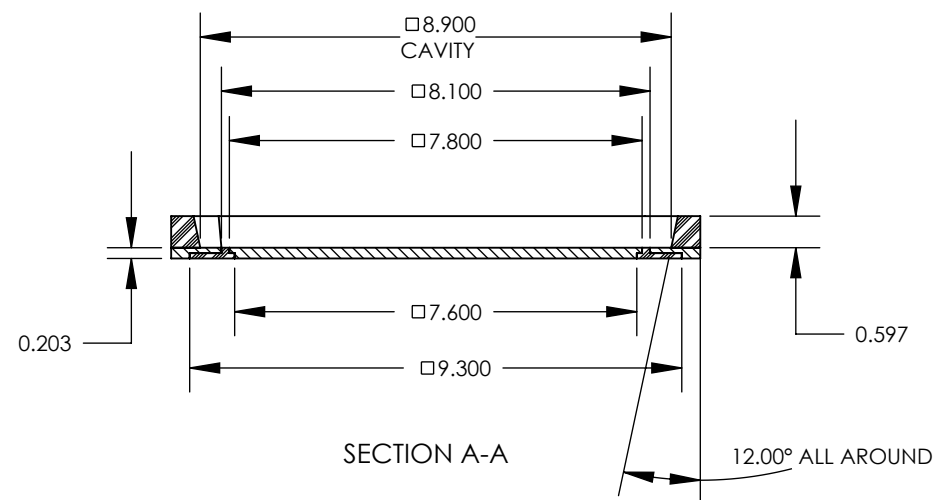


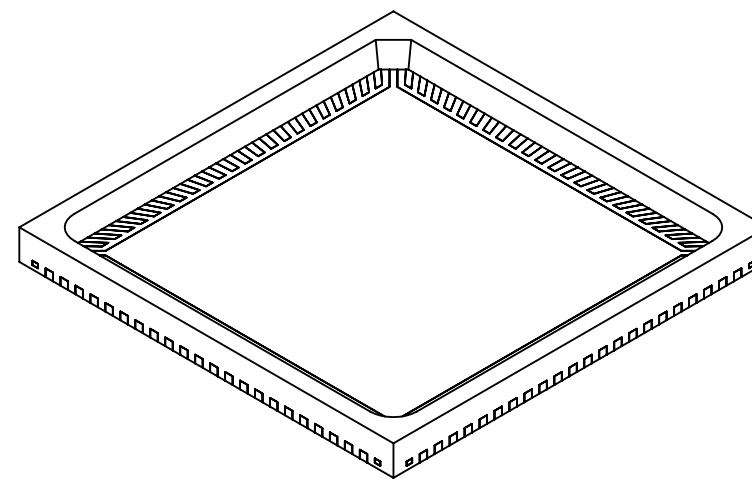
TOP VIEW



BOTTOM VIEW



SECTION A-A



NOTES

- MATERIALS:**
LEAD FRAME: COPPER 194FH, THK = 0.203 ± 0.008
BODY: SEMICONDUCTOR MOLDING EPOXY, CONTACT QPTECHNOLOGIES FOR DETAILS.
- FINISH:**
LEAD FRAME: ELECTROLESS NICKEL PER MIL-C-26074, CLASS 1, 200 TO 300 MICRONS (2.5um-7.6um) THICK.
GOLD PLATE PER MIL-G-45204, TYPE 3, GRADE A, CLASS 1 (40 TO 80 MICRONS (1um-2um) THICK).
BODY SURFACE FINISH: VDI 21-24 (1.12-1.6 Ra)
- PACKAGE MISMATCH:** BODY OFFSET FOR LEAD FRAME = 0.076mm MAX.
- UNLESS OTHERWISE SPECIFIED, RADIUS ON ALL MOLDED EDGES AND CORNERS = 0.25mm MAX.**
- PACKAGE CONFORMS TO JEDEC MO-220**

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		UNLESS OTHERWISE SPECIFIED:				NAME		DATE	
		DIMENSIONS ARE IN MILLIMETERS		DRAWN		D. Abbe		8/10/11	
		TOLERANCES ARE:		CHECKED		S. Swen		8/10/11	
		ANGULAR: ±0.5 degree		ENG APPR.		S. Swen		8/10/11	
		.X = ±0.76 .XX: ±0.25							
		.XXX = ±0.13 .XXXX = ±0.01							
		MATERIAL		COMMENTS:					
		SEE NOTE 1							
NEXT ASSY		USED ON							
		FINISH							
		SEE NOTE 2							
APPLICATION		DO NOT SCALE DRAWING							
				TITLE:		QPTECHNOLOGIES		A DIVISION OF PROMEX INDUSTRIES QPTECHNOLOGIES.COM	
				QP-QFN88-10MM-0.40MM					
SIZE		DWG. NO.		REV					
B		500407		A					
SCALE: 7:1		WEIGHT:		SHEET 1 OF 1					

